

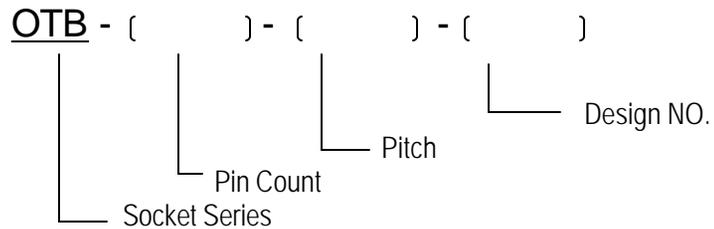
# Micro BGA

# BALL GRID ARRAY

## Applicable IC/Micro BGA

## OPEN TOP TYPE SOCKETS

### ORDERING PROCEDURE

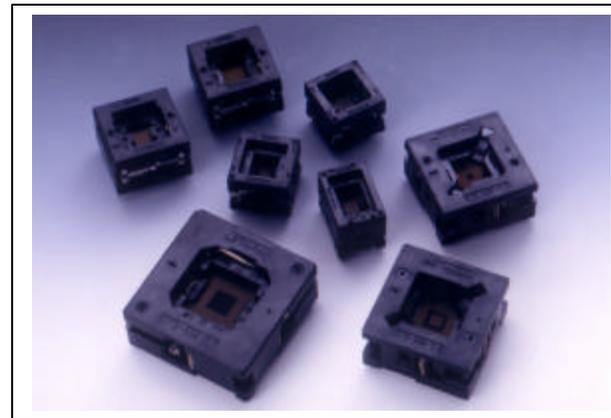


### SPECIFICATIONS

- Contact resistance: Initial 50mΩ (At 10mA)
- Maximum voltage: AC700V RMS (for 1 minute)
- Insulation resistance: 1,000MΩ or higher (At DC 500V)
- Rated current: 1A
- Operating temperature range: -60°C ~ +150°C
- Terminal strength against pulling: 0.5kg (1 minute)
- Insertion: Min. 10,000 times (Mechanical)

### MATERIAL

- Body: PEI, PES
- Contact: BeCu, Au plating (Ni-base)



## APPLICABLE IC DIMENSIONS & SOCKET DIMENSIONS

### OTB-484 SERIES (0.8mm PITCH)

Unit: mm

PART NO.	APPLICABLE IC DIMENSIONS (REF.)					OUTSIDE DIMENSIONS (REF.)				REMARKS
	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B	C	D	
OTB-257(484)-0.8-15	16X16	19X19	Depopulated	257	0.8	48	48	19	2.9	
OTB-280(484)-0.8-23	16X16	19X19	P.5 Row	280	0.8	48	48	19	2.9	
OTB-288(484)-0.8-05	16X16	19X19	Depopulated	288	0.8	48	48	19	2.9	
OTB-332(484)-0.8-03	17X17	19X19	P.7 Row	332	0.8	48	48	19	2.9	
OTB-216(484)-0.8-01	18X18	21X21	P.3 Row	216	0.8	48	48	19	2.9	
OTB-384(484)-0.8-04	18X18	22X22	P.6 Row	384	0.8	48	48	19	2.9	
OTB-400(484)-0.8-22	17X17	20X20	Fully Array	400	0.8	48	48	19	2.3	
OTB-480(484)-0.8-18	19X19	22X22	P.10 Row	480	0.8	48	48	19	2.3	
OTB-156(484)-0.8-16	14X14	16X16	P.3 Row	156	0.8	48	48	19	2.9	
OTB-256(484)-0.8-09	17X17	20X20	P.4 Row	256	0.8	48	48	19	2.9	
OTB-336(484)-0.8-09	17X17	20X20	P.6 Row	336	0.8	48	48	19	2.9	
OTB-216(484)-0.8-01	18X18	21X21	P.3 Row	216	0.8	48	48	19	2.9	

– Depopulated version available.

